

ABSTRACT

A multi-layered adhesive sheet 100 includes a substrate film 106, an adhesive layer 103 formed by coating an adhesive having a specific composition onto the substrate film 106, and a die attachment film 105 laminated on the adhesive layer 103. The multi-layered adhesive sheet 100 employing an adhesive having this specific composition is superior in retention of a die chip 108 during dicing of a silicon wafer 101, the multi-layered adhesive sheet 100 is less likely to come off a ring frame 102 during the dicing of the silicon wafer 101, and it allows for the die attachment film 105 and the adhesive layer 103 to be easily peeled apart during a pick-up operation of a die chip 108.